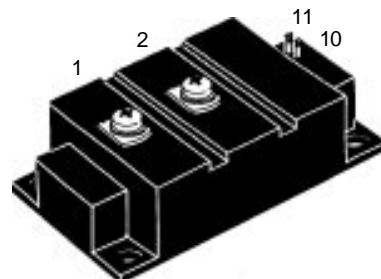
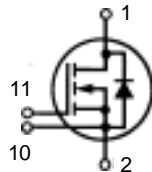


# MegaMOS™ FET Module

## VMO 400-02F

$V_{DSS} = 200\text{ V}$   
 $I_{D25} = 418\text{ A}$   
 $R_{DS(on)} = 4.2\text{ m}\Omega$

N-Channel Enhancement Mode



1 = Drain                      2 = Source  
 10 = Kelvin Source        11 = Gate

Symbol	Test Conditions	Maximum Ratings	
$V_{DSS}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	200	V
$V_{DGR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ ; $R_{GS} = 10\text{ k}\Omega$	200	V
$V_{GS}$	Continuous	$\pm 20$	V
$V_{GSM}$	Transient	$\pm 30$	V
$I_{D25}$	$T_K = 25^\circ\text{C}$	418	A
$I_{DM}$	$T_K = 25^\circ\text{C}$ , $t_p = 10\ \mu\text{s}$	1672	A
$P_D$	$T_C = 25^\circ\text{C}$	2450	W
	$T_K = 25^\circ\text{C}$	1640	W
$T_J$		-40 ... +150	$^\circ\text{C}$
$T_{JM}$		150	$^\circ\text{C}$
$T_{stg}$		-40 ... +125	$^\circ\text{C}$
$V_{ISOL}$	50/60 Hz $t = 1\text{ min}$	3000	V~
	$I_{ISOL} \leq 1\text{ mA}$ $t = 1\text{ s}$	3600	V~
$M_d$	Mounting torque (M6)	2.25-2.75/20-25	Nm/lb.in.
	Terminal connection torque (M5)	2.5-3.7/22-33	Nm/lb.in.
<b>Weight</b>	typical including screws	250	g

### Features

- International standard package
- Direct Copper Bonded  $\text{Al}_2\text{O}_3$  ceramic base plate
- Isolation voltage 3600 V~
- Low  $R_{DS(on)}$  HDMOS™ process
- Low package inductance for high speed switching
- Kelvin Source contact for easy drive

### Applications

- AC motor speed control for electric vehicles
- DC servo and robot drives
- Switched-mode and resonant-mode power supplies
- DC choppers

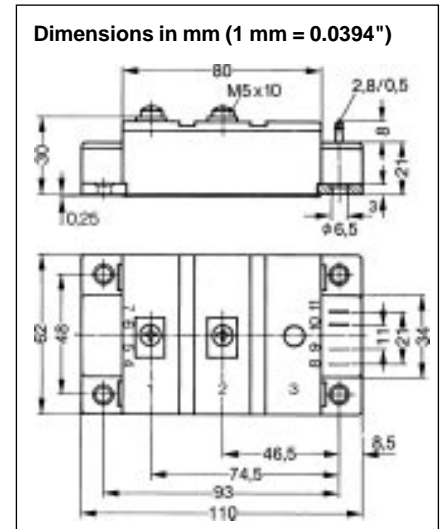
### Advantages

- Easy to mount
- Space and weight savings
- High power density
- Low losses

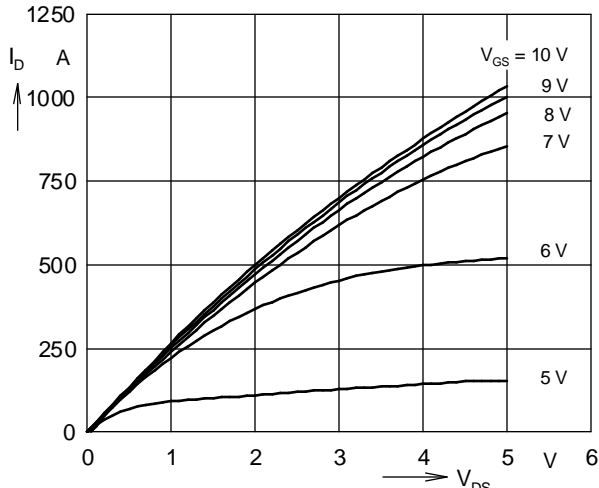
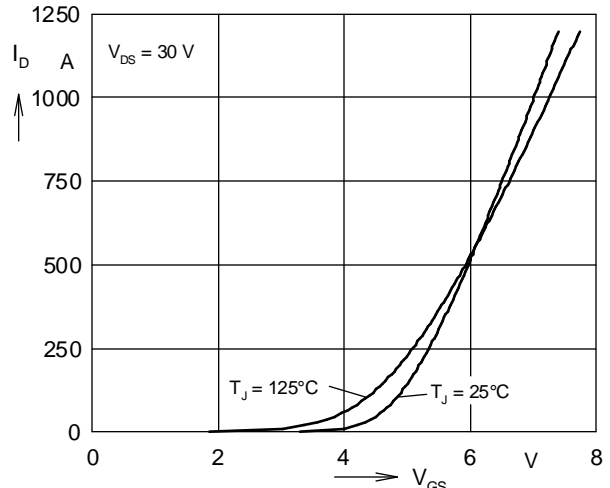
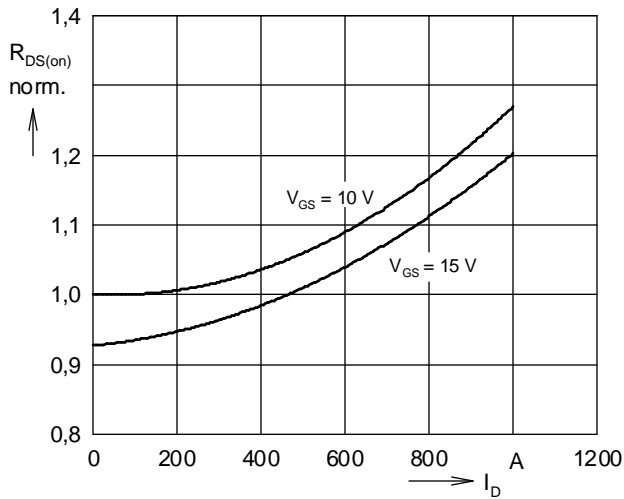
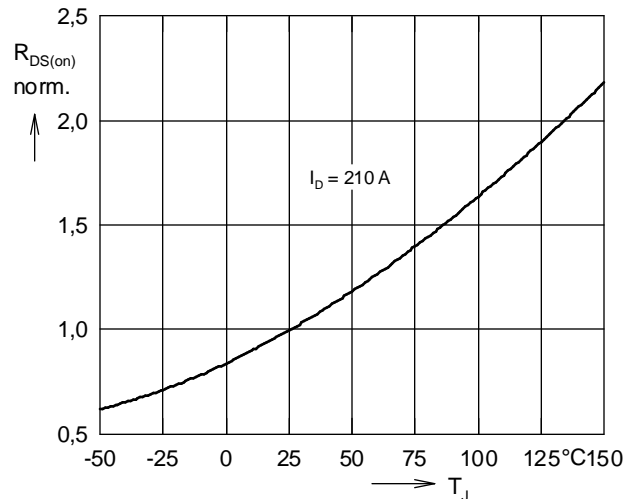
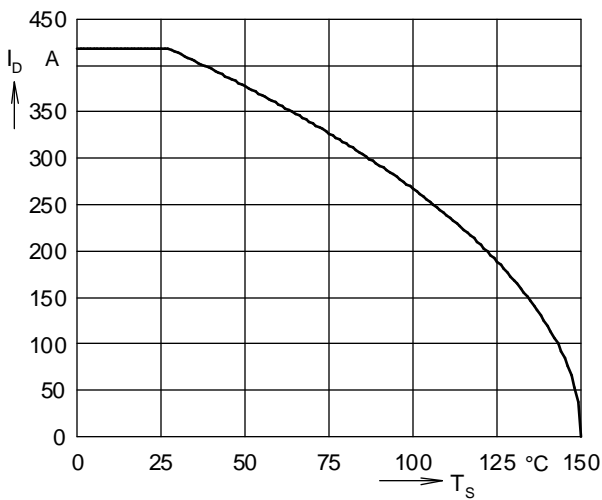
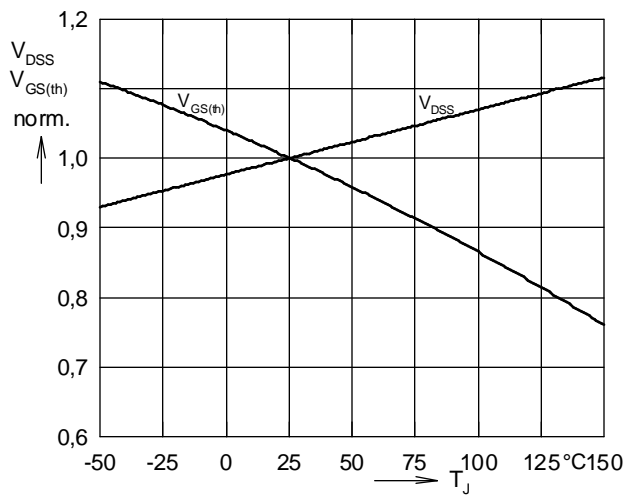
Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$V_{DSS}$	$V_{GS} = 0\text{ V}$ , $I_D = 12\text{ mA}$	200		V
$V_{GS(th)}$	$V_{DS} = 20\text{ V}$ , $I_D = 120\text{ mA}$	3		6 V
$I_{GSS}$	$V_{GS} = \pm 20\text{ V DC}$ , $V_{DS} = 0$			$\pm 500\text{ nA}$
$I_{DSS}$	$V_{DS} = V_{DSS}$ , $V_{GS} = 0\text{ V}$ $T_J = 25^\circ\text{C}$			2.5 mA
	$V_{DS} = 0.8 \cdot V_{DSS}$ , $V_{GS} = 0\text{ V}$ $T_J = 125^\circ\text{C}$			12 mA
$R_{DS(on)}$	$V_{GS} = 10\text{ V}$ , $I_D = 0.5 \cdot I_{D25}$ Pulse test, $t \leq 300\ \mu\text{s}$ , duty cycle $d \leq 2\%$			4.2 m $\Omega$

IXYS reserves the right to change limits, test conditions, and dimensions.

Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$g_{fs}$	$V_{DS} = 10\text{ V}; I_D = 0.5 \cdot I_{D25}$ pulsed		380	S
$C_{iss}$	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$		53	nF
$C_{oss}$			9.6	nF
$C_{rss}$			3.4	nF
$t_{d(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$ $R_G = 1\ \Omega$ (External)		210	ns
$t_r$			500	ns
$t_{d(off)}$			900	ns
$t_f$			350	ns
$Q_g$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$		2300	nC
$Q_{gs}$			420	nC
$Q_{gd}$			1150	nC
$R_{thJC}$				0.051 K/W
$R_{thJK}$	with 30 $\mu\text{m}$ heat transfer paste			0.076 K/W



Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$I_S$	$V_{GS} = 0\text{ V}$			418 A
$I_{SM}$	Repetitive; pulse width limited by $T_{JM}$			1672 A
$V_{SD}$	$I_F = I_S; V_{GS} = 0\text{ V}$ , Pulse test, $t \leq 300\ \mu\text{s}$ , duty cycle $d \leq 2\%$		0.9	1.2 V
$t_{rr}$	$I_F = I_S, -di/dt = 1200\text{ A}/\mu\text{s}, V_{DS} = 100\text{ V}$		600	ns


 Fig. 1 Typical output characteristics  $I_D = f(V_{DS})$ 

 Fig. 2 Typical transfer characteristics  $I_D = f(V_{GS})$ 

 Fig. 3 Typical  $R_{DS(on)} = f(I_D)$ , normalized

 Fig. 4  $R_{DS(on)} = f(T_J)$ , normalized

 Fig. 5 Continuous drain current  $I_D = f(T_K)$ 

 Fig. 6  $V_{DS} = f(T_J)$ ,  $V_{GS(th)} = f(T_J)$ , normalized

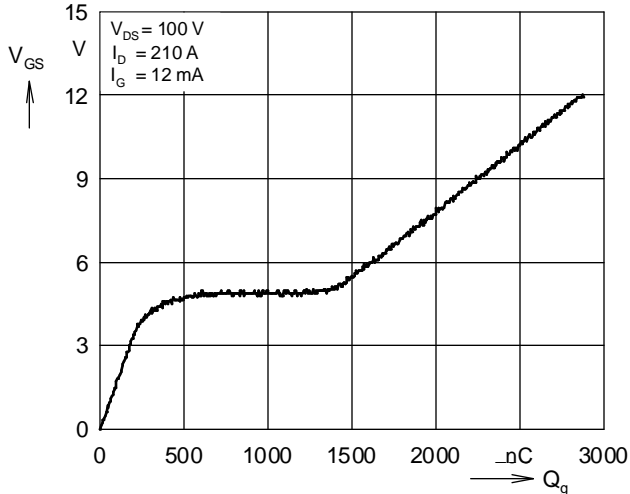


Fig. 7 Typical turn-on gate charge characteristics

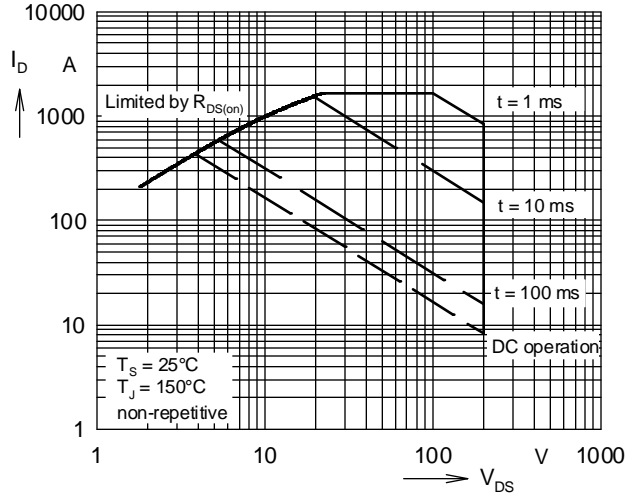
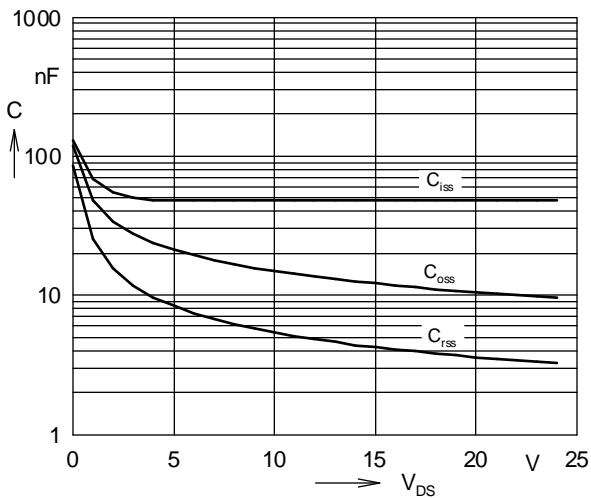
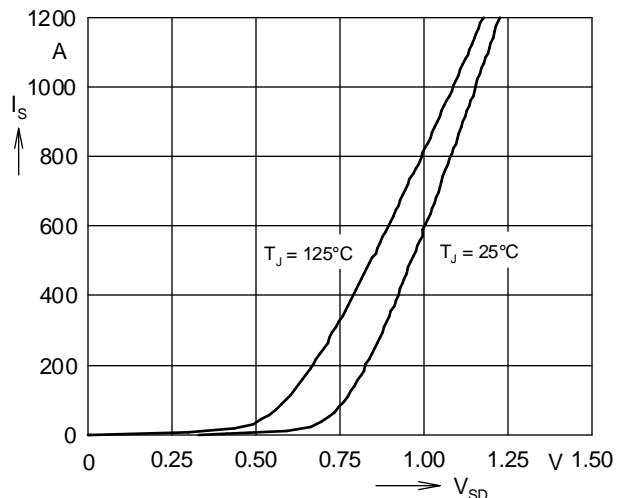
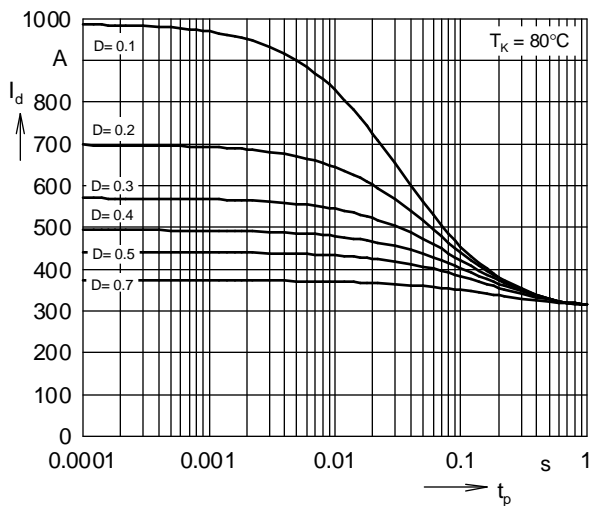
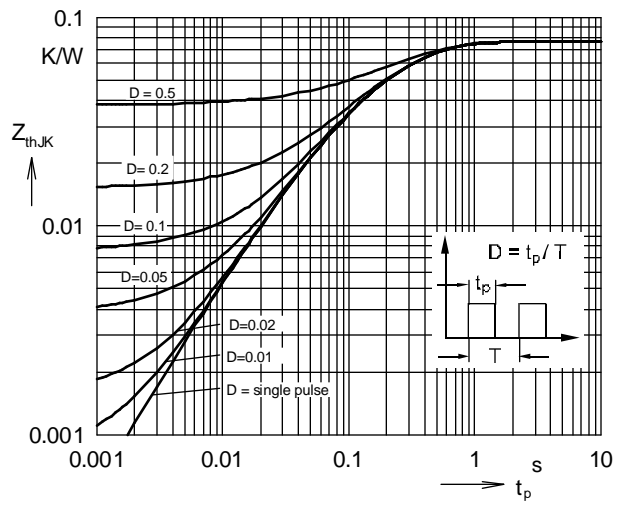

 Fig. 8 Forward Bias Safe Operating Area,  $I_D = f(V_{DS})$ 

 Fig. 9 Typical capacitances  $C = f(V_{DS})$ ,  $f = 1 \text{ MHz}$ 

 Fig. 10 Typical forward characteristics of reverse diode,  $I_S = f(V_{SD})$ 


Fig. 11 Drain current versus pulse width and duty cycle


 Fig. 12 Transient thermal resistance  $Z_{thJK} = f(t_p)$